

Notice of References Cited	Application/Control No. 10/804,737	Applicant(s)/Patent Under Reexamination ICHITSUBO ET AL.	
	Examiner Monica Lewis	Art Unit 2822	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
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FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Tie Wang et al., Assessment of Flip Chip Assembly and Reliability via Reflowable Undefill, 2001, IEEE, 2001 Electronic Components and Technology Conference.
	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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